



#16 response
Duncan
11.7.02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION OF

NAKAGAWA

Appln. No.: 09/654,412

Filed: September 1, 2000

Title: COMPONENT MOUNTING CIRCUIT BOARD WITH RESIN-MOLDED SECTION
COVERING CIRCUIT PATTERN AND INNER COMPONENTS

Confirmation No.: 5709

Group Art Unit: 2841

Examiner: PHAN, THANH S.

October 31, 2002

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AMENDMENT

Hon. Commissioner of Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated July 31, 2002, please reconsider based on the following REMARKS.

REMARKS

Reconsideration and allowance of this application are respectfully requested. The rejection of claim 1 under 35 U.S.C. Section 103(a) as being unpatentable over Fukui et al. in view of Coucoulas is respectfully traversed.

Fukui et al. disclose a technique for fabricating a wiring unit. Their invention pertains in general to the same technical field as our claim 1 invention. Coucoulas, on the other hand, discloses a technique for packaging an integrated circuit and belongs to a technical field quite differing from that of our claim 1 invention. Coucoulas is non-analogous prior art and would be inappropriate to combine the teachings of Coucoulas with those of Fukui et al.

Furthermore, Fukui et al. disclose nothing about a technique for covering an inner electrical component connected to a circuit pattern with molded resin. Our claim 1 invention however provides a technique for covering an inner electrical component connected to a circuit pattern with molded resin. This technique is quite new in the field of circuit board design and construction.

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